

<b>PCN Number:</b>	20170407000	<b>PCN Date:</b>	Apr 28, 2017
<b>Title:</b>	Qualification of CFAB as an additional wafer fab site option for select devices in LBC5 process technology		
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>	Jul 28, 2017	<b>Estimated Sample Availability:</b>	Date provided at sample request.
<b>Change Type:</b>			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>		<input type="checkbox"/>	Packing/Shipping/Labeling
<input checked="" type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Test Process
<input checked="" type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Part number change

### PCN Details

#### Description of Change:

This change notification is to announce the qualification of CFAB as an additional wafer fab site option for the LBC5 devices listed in the product affected section of this document.

Current Sites				Additional Sites			
Current Fab Site	Fab Process	Bump Site	Wafer Diameter	Additional Fab Site	Fab Process	Bump Site	Wafer Diameter
DP1DM5	LBC5	DBUMP	200 mm	CFAB	LBC5	Clark-BP	200 mm

The LBC5 process technology has been running successfully in production at CFAB since 2012.

#### Reason for Change:

Continuity of Supply

#### Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

#### Changes to product identification resulting from this PCN:

##### Current:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DP1DM5	DM5	USA	Dallas

##### New:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
<b>CFAB</b>	<b>CU3</b>	<b>CHN</b>	<b>Chengdu</b>


Sample product shipping label (not actual product label)



MADE IN: Malaysia  
2DC: 2d:

MSL 2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

OPT:  
ITEM: 39  
**LBL: 5A (L)TO:1750**




(1P) SN74LS07NSR  
(Q) 2000 (D) 0336  
(31T) LOT: 3959047MLA  
(4W) TKY (1T) 7523483S12  
(P)  
(2P) REV: (V) 0033317  
(20L) CS0: SHP (21L) CC0: USA  
(22L) AS0: MLA (23L) AC0: MYS

#### Product Affected:

DRV8313PWP	DRV8803PWPR	DRV8805PWP	DRV8844PWP
DRV8313PWPR	DRV8804PWP	DRV8805PWPR	DRV8844PWPR
DRV8803PWP	DRV8804PWPR		

**Qualification Report**

**CFAB OFFLOAD FROM DMO5 – Moobot (DRV8803PWPR)**  
Approve Date 12-Nov-2015

**Product Attributes**

Die Attributes	Qual Device: C8803A0A	QBS Product Reference: DRV8803PWP	QBS Product Reference: DRV8804DW-P	QBS Process Reference: TA S5613APHD	QBS Package Reference: BUF11704AIPWPR	QBS Package Reference: TPA1517DWP	QBS Package Reference: TPS40057PWP	QBS Package Reference: TPS56161PWP
Assembly Site	TITL	TI TAIWAN	MLA (TIM)	TAI (TITL)	TAI	TAI	TAI	TAI
Package Family	HTSSOP	HTSSOP	SOIC - DW	HTQFP	TSSOP	SOIC	TSSOP	TSSOP
Wafer Fab Supplier	CFAB	DM5	DM5	CFAB	DMOS5	SFAB	DFAB	DFAB
Wafer Process	LBC5	LBC-5X	LBC5	LBC5	50HPA07	Bipolar	LBC4	LBC4x

- QBS: Qual By Similarity  
- Qual Device C8803A0A is qualified at LEVEL3-260CG

**Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: C8803A0A	QBS Product Reference: DRV8803PWP	QBS Product Reference: DRV8804DW-P	QBS Process Reference: TA S5613APHD	QBS Package Reference: BUF11704AIPWPR	QBS Package Reference: TPA1517DWP	QBS Package Reference: TPS40057PWP	QBS Package Reference: TPS56161PWP
AC	Autoclave 121C	96 Hours	-	-	-	3/231/0	1/77/0	3/231/0	1/77/0	1/77/0
ED	Electrical Characterization	Per Datasheet Parameters	Pass	-	Pass	Pass	-	-	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	3/231/0	-	3/78/0	-	-
HBM	ESD - HBM	3000 V	-	-	1/3/0	-	-	-	-	-
CDM	ESD - CDM	1500 V	-	1/3/0	1/3/0	-	-	-	-	-
HTOL	Life Test, 125C	1000 Hours	-	-	-	-	-	3/120/0	-	-
HTOL	Life Test, 155C	240 Hours	-	-	-	3/231/0	-	-	-	-
HTSL	High Temp. Storage/Bake, 170C	420 Hours	-	-	-	3/230/0	1/77/0	3/231/0	1/77/0	1/77/0
LU	Latch-up	(per JEDEC78)	-	-	1/6/0	3/18/0	-	-	-	-
SBS	Ball Shear	Wires	-	-	-	-	1/76/0	-	-	-
TC	Temperature Cycle -65C/150C	500 Cycles	-	2/154/0	3/231/0	3/231/0	1/77/0	3/231/0	1/77/0	1/77/0
TS	Thermal Shock, -65/150C	500 Cycles	-	-	-	-	1/77/0	3/231/0	1/77/0	1/77/0
WBP	Bond Pull	Wires	-	-	-	-	1/76/0	3/228/0	-	-
WBS	Bond Shear	Wires	-	-	-	-	-	3/228/0	-	-

- Preconditioning was performed for Autoclave, Unbiased HAST, HB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable  
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours  
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours  
- The following are equivalent Temp Cycle options per JEDEC47: -55C/125C/700 Cycles and -65C/150C/500 Cycles  
Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>  
Green/Pb-Free Status:  
Qualified Pb-Free (SMT) and Green

**Qualification Report**

**CFAB OFFLOAD from DMO5 (DRV8844PWPR)**  
Approve Date 12-Nov-2015

**Product Attributes**

Die Attributes	Qual Device: C8844A1	QBS Product Reference: DRV8844PWP	QBS Process Reference: TA S5613APHD	QBS Package Reference: BUF11704AIPWPR	QBS Package Reference: TPA1517DWP	QBS Package Reference: TPS40057PWP	QBS Package Reference: TPS56161PWP
Assembly Site	TITL	TAI	TAI (TITL)	TAI	TAI	TAI	TAI
Package Family	HTSSOP	-	HTQFP	TSSOP	SOIC	TSSOP	TSSOP
Wafer Fab Supplier	CFAB	DMOS5	CFAB	DMOS5	SFAB	DFAB	DFAB
Wafer Process	LBC5	LBC5X	LBC5	50HPA07	Bipolar	LBC4	LBC4x

- QBS: Qual By Similarity  
- Qual Device C8844A1 is qualified at LEVEL3-260CG

**Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: C8844A1	QBS Product Reference: DRV8844PWP	QBS Process Reference: TA S5613APHD	QBS Package Reference: BUF11704AIPWPR	QBS Package Reference: TPA1517DWP	QBS Package Reference: TPS40057PWP	QBS Package Reference: TPS56161PWP
AC	Autoclave 121C	96 Hours	-	-	3/231/0	1/77/0	3/231/0	1/77/0	1/77/0
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	1/30/0	1/30/0	-	-	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	3/231/0	-	3/78/0	-	-
HBM	ESD - HBM	3000 V	-	1/3/0	-	-	-	-	-
CDM	ESD - CDM	1500 V	-	1/3/0	-	-	-	-	-
HTOL	Life Test, 125C	1000 Hours	-	-	-	-	3/120/0	-	-
HTOL	Life Test, 155C	240 Hours	-	-	3/231/0	-	-	-	-
HTSL	High Temp. Storage/Bake, 170C	420 Hours	-	-	3/230/0	1/77/0	3/231/0	1/77/0	1/77/0
LU	Latch-up	(per JEDEC78)	-	2/12/0	3/18/0	-	-	-	-
SBS	Ball Shear	Wires	-	-	-	1/76/0	-	-	-
TC	Temperature Cycle -65/150C	500 Cycles	-	1/77/0	3/231/0	1/77/0	3/231/0	1/77/0	1/77/0
TS	Thermal Shock, -65/150C	500 Cycles	-	-	-	1/77/0	3/231/0	1/77/0	1/77/0
WBP	Bond Pull	Wires	-	-	-	1/76/0	3/228/0	-	-
WBS	Bond Shear	Wires	-	-	-	-	3/228/0	-	-

- Preconditioning was performed for Autoclave, Unbiased HAST, HB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable  
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours  
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours  
- The following are equivalent Temp Cycle options per JEDEC47: -55C/125C/700 Cycles and -65C/150C/500 Cycles  
Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>  
Green/Pb-Free Status:  
Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

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Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
Japan	<a href="mailto:PCNJapanContact@list.ti.com">PCNJapanContact@list.ti.com</a>